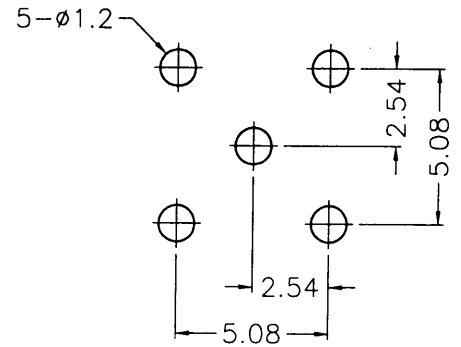
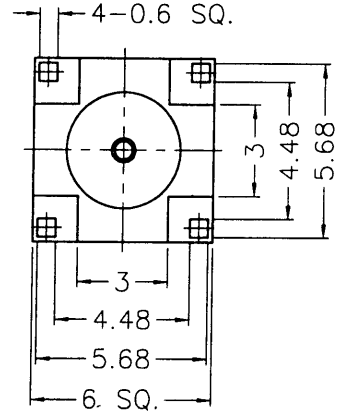
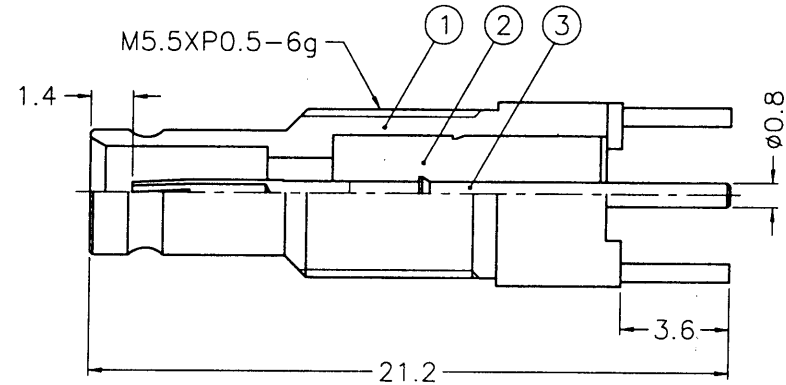
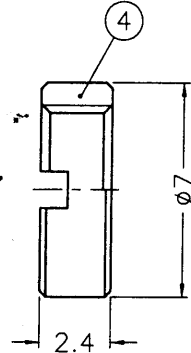


1 2 3 4 5 6 7 8

REVISIONS		
ISS	ZONE	DESCRIPTION\PER REQUEST\DATE



PCB MOUNTING HOLE
(印刷电路板架設孔)



- NOTES: FINISH (PLATING THICKNESS IN MICRO-INCHES)
1. BRASS PER QQ-B-626
 2. BERYLLIUM COPPER PER QQ-C-530
 3. NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 4. GOLD PL. 3 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 5. GOLD PL. 30 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 6. TEFLON MIL-P-19468



DIMENSIONS ARE IN MILLIMETERS				PART NO.	
UNLESS OTHERWISE SPECIFIED TOLERANCES				APPROVED	DATE
0.5-6 = ±0.2				<i>Andy C</i>	05-20-03'
6-30 = ±0.4				CHECKED	DATE
30-120 = ±0.6				<i>Andy C</i>	05-20-03'
120-315 = ±1				DRAWN	DATE
315-1000 = ±1.6				JOYCE	05-20-03'
1000-2000 = ±2.4				FILE NO.	F:\DWG\123\6251L1\003\75\N3GT30G

Amphenol
Danbury, CT, USA - Tainan, Taiwan - Shenzhen, China

TITLE: 1.0/2.3 PCB JACK

DRAWING NO.: 1236251L1-003-N/3GT30G-75

ITEM NO.:

NO.	DESCRIPTION	MATERIAL	FINISH	Q'TY	DRAWING NO.
4	SPANNER NUT	NOTE 1	NOTE 3	1	123-JACK-SN
3	CONTACT PIN	NOTE 2	NOTE 5	1	
2	INSULATOR	NOTE 6	NATURAL	1	
1	BODY	NOTE 1	NOTE 4	1	

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1 2 3 4 5 6 7 8